

#5/A

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: Y. SHIMADA, et al.
Application No.: TBD
Filed: January 18, 2005
For: MULTILAYER WIRING BOARD, MANUFACTURING METHOD
THEREOF, SEMICONDUCTOR DEVICE, AND WIRELESS
ELECTRONIC DEVICE
Group: TBD
Examiner: TBD

PRELIMINARY AMENDMENT

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

January 18, 2005

Sir:

Please amend the above-identified application, prior to calculation of the filing fee, as listed in the following, and as set forth on the following pages:

Amendments to the Claims; and

Remarks are included following the amendments.